



Product/Process Change Notification Form

PCN Number:	PCN-2019-535
Date of Notification:	3/8/2019
Apex P/N(s):	PA164PQ, PA165PQ, CD33
Date PCN Effective:	3/15/2019
Reason for Change:	<input type="checkbox"/> Design /New Rev. <input type="checkbox"/> Assembly Site <input type="checkbox"/> Assembly Process <input type="checkbox"/> Spec Limit Change <input checked="" type="checkbox"/> Other (specify) The material used for PA164PQ and PA165PQ package encapsulation is changed.
Description of Change:	To improve the package resistance to solder heat and repeated exposure to solder reflow temperature during device solder attach to a PCB, the material used for package encapsulation is changing.
Apex P/N Change:	<input type="checkbox"/> Yes, New Part Number: <input checked="" type="checkbox"/> No
Lot Effective Date:	1909 Product incorporating this change may be shipped interchangeably with existing unchanged products.
Quality & Reliability impact:	Qualification Data: <input type="checkbox"/> Required <input checked="" type="checkbox"/> Not Required
Datasheet Change Required?	<input type="checkbox"/> Yes <input checked="" type="checkbox"/> No If Yes, briefly explain:

Acknowledgement of Receipt of Notice:

Company Name: _____
Name (please print): _____ **Title:** _____
Signature: _____ **Date:** _____

Customer Representative is to obtain the customer acknowledgement/signature and return this notification to Apex Microtechnology, attn: PCN administrator at email to custserv@apexanalog.com.

**NOTE: Lack of acknowledgement within 30 days of the date of notice, constitutes acceptance of change.
(Reference JEDEC Industry Standard: JESD-46)**